RF surface aspects at power couplers

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Ceramic fabrication and treatment

Career of the ceramic (TTF Coupler)

Preconditions

- One supplier for quality stability
- One batch of powder for one seriens fabrication
- Measurement of tang δ and ϵ in the lab
- Sintering at the supplier

> at the coupler fabrication:

	СРІ	RI
Firing at air, inspection	in house	at supplier
Metallization	in house	at supplier
800C in vacuum	-	in house
Brazing	in house	in house
Inspection and sand blasting if necessary	in house	in house
TiN coat	in house	in house
E- beam welding	subcontract	in house
Inspection	in house	in house



Ceramics after brazing





Ceramic inspection after brazing, before TiN coating



Appeared after brazing, is inside the material and cannot removed by surface sand blasting

Appeared after brazing on surface, can be removed by sand blasting







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Ceramic inspection after e-beam welding







No TiN - can be sand blasted

Copper evaporation from e-beam welding, Cannot be removed because TiN would be damaged



Metallic residues from friction with tooling



Edge broken, ceramic has to be replaced

- Can be sand blasted when not TiN coated
- Otherwise ceramic replacement



Ceramics after RF operation

- After RF conditioning on test stand
- Dark stains
- Origin unknown
- Analysis underway









Ceramic must be replaced

Ceramics after RF operation

Wave guide window after years of operation

Brown discoloration due to X-ray

 Gray discoloration unknown, no electrical resistance

Can be used without restrictions



Ceramics after RF operation

Wave guide window after month of operation

- Strong vacuum and light activities
- Gray discoloration unknown, brown comes from X-ray
- no electrical resistance measured (measurement days after disassembly)
- No increase of thermal heating observed



Looks like metallization => window was exchanged,



Copper plating before RF conditioning

Bellow valley

- Circular defects
 - With copper
 - Without copper
 - Multiple holes

Questions:

- How many acceptable?
- Outgassing?
- SEC?



Copper plating before RF conditioning

Bellow valley

missing copper

Question:

- Acceptable?
- Up to what size?



Copper plating before RF conditioning

Bellow valley

Particles on surface and embedded

- Loose particles and sharp edges => not accepted
- Some could be removed
- Embedded particles with soft edges are accepted





Copper plating after RF conditioning

- Discoloration on copper
- Can be removed by citric acid => must be CuO
- RGA is OK

Acceptable?









Copper plating after RF operating in modules (FLASH)

- Many stains and discolorations
- No restrictions during operation
- No hints in RGA





Acceptable?









Questions

> What are the surface roughness limitations by scratches (brushing)?

- see Chris's talk at TTC
- What is the source of stains and discolorations after RF operation at ceramics and at copper?
- > Do we need to prevent stains and discolorations and how?



